Name of the part	Pb	Cd	Hg	Cr-VI	PBB	PBDE
Die	X	O	O	O	O	O
Lead Frame	O	O	O	O	O	O
Mould Compound	O	O	O	O	O	O
Post-plating	O	O	O	O	O	O
Solder Wire	X	O	O	O	O	O
Wire	O	O	O	O	O	O

O: Indicates all homogeneous materials` hazardous substances content are below the SJ/T11363-2006 limit.

X: Indicates that the hazardous substance content contained in any one of the homogenuous materials of the part exceeded the MCV limits specified in the Standard SJ/T 11363-2006.

Remark: All WeEn Semiconductors products have an environmental friendly use period (EFUP) of 50 years.

Disclaimer All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.